BOM-TIDA-01387.xls
None
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TIDA-01387 REV E1 Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
!PCB	1		TIDA-xxxxx	Any	Printed Circuit Board	
C1, C2	1	20F	KAMAP	KAMAP	CAP, AL, 20 F, 5.4 V, +/- 20%,	
C3, C4, C9, C10	4	470uF	6SEPC470MW	Panasonic	CAP, AL, 470 µF, 6.3 V, +/- 20%, 0.007 ohm, TH	6.3x9mm
C5	1	10uF	GRM188R60J106ME84	MuRata	CAP, CERM, 10 µF, 6.3 V, +/- 20%, X5R, 0603	0603
C6	1	0.1uF	GRM188R71C104KA01D	MuRata	CAP, CERM, 0.1 µF, 16 V, +/- 10%, X7R, 0603	0603
C7	1	100pF	C0603C0G1E101J030BA	TDK	CAP, CERM, 100 pF, 25 V, +/- 5%, C0G/NP0, 0201	0201
C8	1	22uF	C1608X5R0J226M080AC	TDK	CAP, CERM, 22 µF, 6.3 V, +/- 20%, X5R, 0603	0603
D1	1	5.1V	1SMB5918BT3G	ON Semiconductor	Diode, Zener, 5.1 V, 550 mW, SMB	SMB
FID1, FID2, FID3	3		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
H1, H2, H3, H4	4		NY PMS 440 0025 PH	B&F Fastener Supply	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw
H5, H6, H7, H8	4		1902C	Keystone	Standoff, Hex, 0.5"L #4-40 Nylon	Standoff
H9, H10, H11, H12	4		SJ-5303 (CLEAR)	3M	Bumpon, Hemisphere, 0.44 X 0.20, Clear	Transparent Bumpon
J1, J2	2		TSW-104-07-G-S	Samtec	Header, 100mil, 4x1, Gold, TH	4x1 Header
J3	1		TSW-103-07-T-S	Samtec	Header, 2.54 mm, 3x1, Tin, TH	Header, 2.54 mm, 3x1, TH
L1	1	470nH	XFL4015-471MEC	Coilcraft	Inductor, Shielded, Composite, 470 nH, 3.5 A, 0.0076 ohm, SMD	SMD, 4x4x1.5mm
MF1, MF2	2	0.04	CSRN2010FK40L0	Stackpole Electronics Inc	RES, 0.04, 1%, 1 W, 2010	2010
R1	1	402k	RC0603FR-07402KL	Yageo America	RES, 402 k, 1%, 0.1 W, 0603	0603
R2	1	100k	CPF0603B100KE	TE Connectivity	RES, 100 k, 0.1%, 0.063 W, 0603	0603
R3	1	1.00k	CRCW06031K00FKEA	Vishay-Dale	RES, 1.00 k, 1%, 0.1 W, 0603	0603
R4, R5	2	58.3	RT0603BRD0758R3L	Yageo America	RES, 58.3, 0.1%, 0.1 W, 0603	0603
TP1	1		1502-2	Keystone	Terminal, Turret, TH, Double	Keystone1502-2
U1	1		TPS61021ADSGR	Texas Instruments	3-A BOOST CONVERTER WITH 0.5V ULTRA-LOW INPUT VOLTAGE, DSG0008A	DSG0008A
U2	1		Used in BOM report	Used in BOM report		eg: 0603, used in PnP report

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